

【ABSTRACT】

The present invention relates to a copper alloy strip material for use in electrical or electronic parts, including: a copper alloy comprising 2.0 to 5.0 mass% Ni, 0.43 to 1.5 mass% Si, and the balance of Cu and unavoidable impurities, wherein there are three types of intermetallic compounds (A, B and C) comprising Ni and Si in a total amount of 50 mass% or more, the intermetallic compound A having a compound diameter (which is an arithmetic mean between a minimum value and a maximum value in the compound diameters, and hereinafter, it is defined as the same meaning) of 0.3 μm to 2 μm , the intermetallic compound B having a compound diameter of 0.05 μm to less than 0.3 μm , and the intermetallic compound C having a compound diameter of more than 0.001 μm to less than 0.05 μm .

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